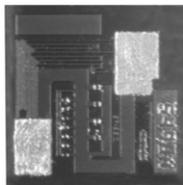


## Thin Film Top-Contact Resistor with Part Mark



Product may not be to scale

The SFP series single-value resistor chips offer a small size, wide ohmic value range and excellent power capacity. The SFPs are part marked with resistance value allowing user the ability to visually determine the resistance value of the chip. The SFPs are manufactured using Vishay Electro-Films (EFI) sophisticated thin film equipment and manufacturing technology. The SFPs are 100 % electrically tested and visually inspected to MIL-STD-883.

### FEATURES

- Wire bondable
- Part marked - 5 digits
- Small size: 0.022 inches square
- Resistance range: 1 Ω to 1 MΩ
- DC power rating: 250 mW
- Oxidized silicon substrate for good power dissipation
- Resistor material: Tantalum nitride, self passivating
- Moisture resistant

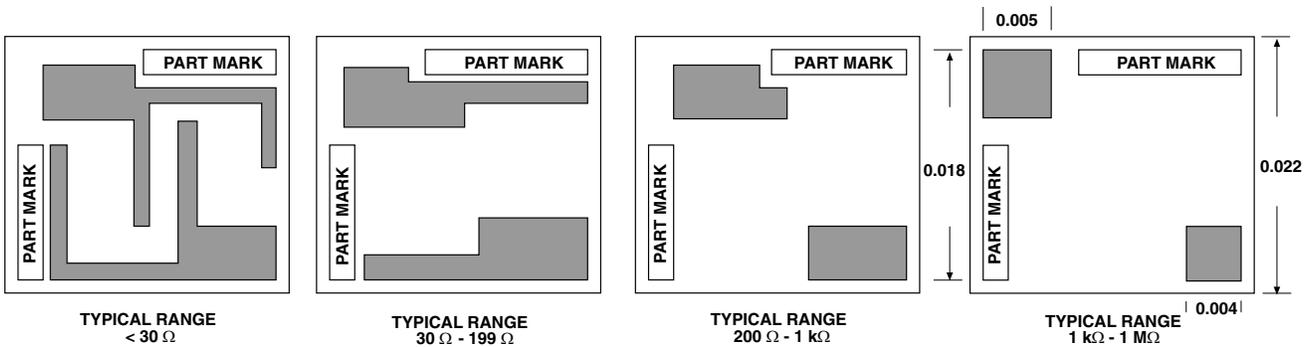
### APPLICATIONS

Vishay EFI SFP small resistor chips are widely used in hybrid packages where space is limited and chip value marking is important for identification. The die is part marked with the resistance value. Wire bonding is made to the two pads on the top of the chip.

TEMPERATURE COEFFICIENT OF RESISTANCE, VALUES AND TOLERANCES													
<p>Tightest Standard Tolerance Available</p>													
<table border="1"> <thead> <tr> <th colspan="2">PROCESS CODE</th> </tr> <tr> <th>CLASS H*</th> <th>CLASS K*</th> </tr> </thead> <tbody> <tr> <td>103</td> <td>108</td> </tr> <tr> <td>102</td> <td>107</td> </tr> <tr> <td>101</td> <td>106</td> </tr> <tr> <td>100</td> <td>105</td> </tr> </tbody> </table>		PROCESS CODE		CLASS H*	CLASS K*	103	108	102	107	101	106	100	105
PROCESS CODE													
CLASS H*	CLASS K*												
103	108												
102	107												
101	106												
100	105												
<p>* MIL-PRF-38534 inspection criteria</p>													

STANDARD ELECTRICAL SPECIFICATIONS	
PARAMETER	
Noise, MIL-STD-202, Method 308 100 Ω - 250 kΩ < 100 Ω or > 251 kΩ	- 35 dB typ. - 20 dB typ.
Moisture Resistance, MIL-STD-202 Method 106	± 0.5 % max. ΔR/R
Stability, 1000 h, + 125 °C, 125 mW	± 0.25 % max. ΔR/R
Operating Temperature Range	- 55 °C to + 125 °C
Thermal Shock, MIL-STD-202, Method 107, Test Condition F	± 0.25 % max. ΔR/R
High Temperature Exposure, + 150 °C, 100 h	± 0.5 % max. ΔR/R
Dielectric Voltage Breakdown	200 V
Insulation Resistance	10 <sup>12</sup> min.
Operating Voltage	100 V max.
DC Power Rating at + 70 °C (Derated to Zero at + 175 °C)	250 mW
5 x Rated Power Short-Time Overload, + 25 °C, 5 s	± 0.25 % max. ΔR/R

Values above 1M available

**DIMENSIONS** in inches

**SCHEMATIC**


**STANDARD MARKING - 5 DIGITS**

<b>XXXX</b>	<b>X</b>
Four significant digits of value	Multiplier
	C = 0.001
	B = 0.01
	A = 0.1
	0 = 0
	1 = 10
	2 = 100
	3 = 1000

<b>MECHANICAL SPECIFICATIONS</b> in inches	
PARAMETER	
Chip Size	0.022 x 0.022 ± 0.003 (0.558 x 0.558 ± 0.05 mm)
Chip Thickness	0.010 ± 0.002 (0.254 ± 0.05 mm)
Chip Substrate Material	Oxidized silicon, 10 kÅ minimum SiO <sub>2</sub>
Resistor Material	Tantalum nitride, self-passivating
Bonding Pad Size	0.004 x 0.004 (0.10 x 0.10 mm)
Number of Pads	2
Pad Material	25 kÅ minimum aluminum
Backing	None, lapped semiconductor silicon

**Options:** Gold backing for eutectic die attach  
 Gold bonding pads, 15 kÅ minimum thickness  
 Consult Applications Engineer

<b>ORDERING INFORMATION</b>					
Example: 100 % visual, 10 kΩ, ± 1 %, ± 250 ppm/°C TCR, aluminum pads, class H visual inspection					
<b>W</b>	<b>SFP</b>	<b>100</b>	<b>1000</b>	<b>1</b>	<b>F</b>
INSPECTION	PRODUCT	PROCESS	RESISTANCE	MULTIPLIER	TOLERANCE
/PACKAGING	FAMILY	CODE	VALUE	CODE	CODE
W = 100 % visually inspected parts in matrix tray per MIL-STD-883		See Process Code table	Use first 4 digits of the resistance	B = 0.01 A = 0.1 0 = 1 1 = 10 2 = 100 3 = 1000 4 = 10000	B = 0.1 % C = 0.2 % D = 0.5 % F = 1.0 % G = 2.0 % H = 2.5 % J = 5.0 % K = 10 %
X = Sample, commercial visually inspected parts loaded in matrix trays (4 % AQL)					*Coating standard



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